

规格书编号

SPEC NO :

产品规格书

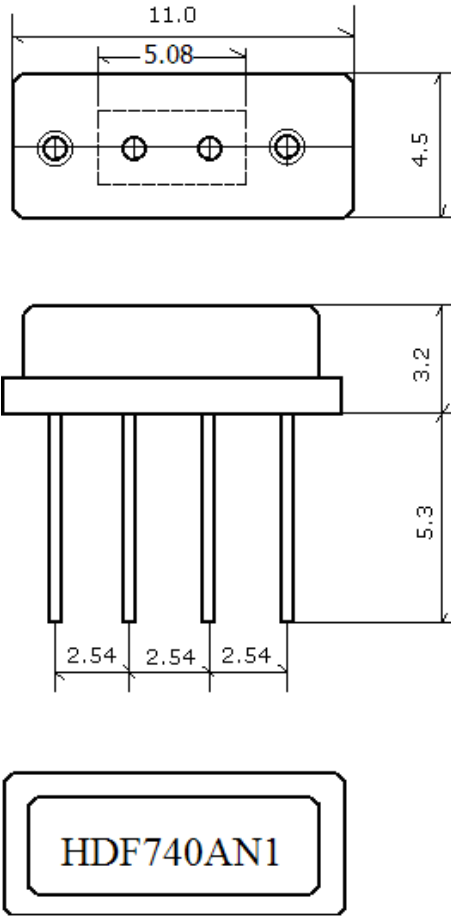
SPECIFICATION

CUSTOMER 客户: _____
PRODUCT 产品: _____ SAW FILTER _____
MODEL NO 型号: _____ HDF740AN1-F11 _____
PREPARED 编制: _____ CHECKED 审核: _____
APPROVED 批准: _____ D A T E 日期: _____ 2012-11-13 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. DIMENSION



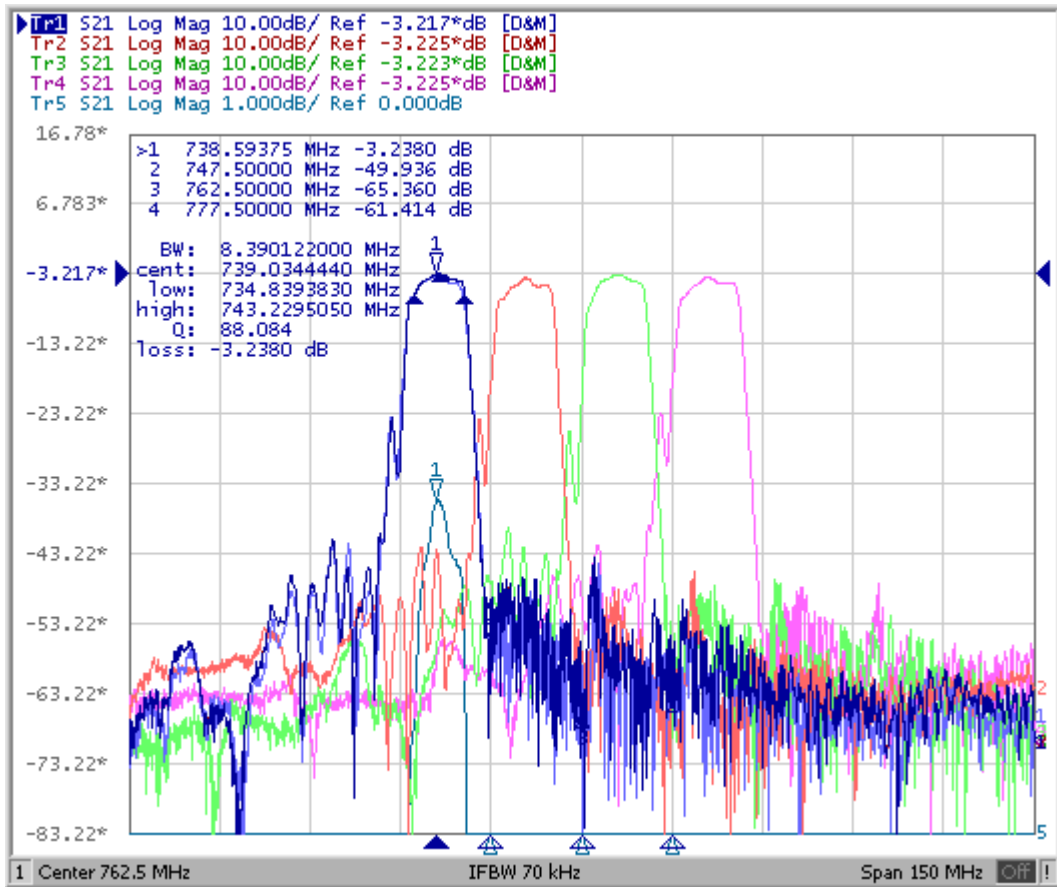
2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
Storage Temperature Range	-40°C to +85°C
Operation Temperature Range	-40°C to +85°C
RF Power	10dBm

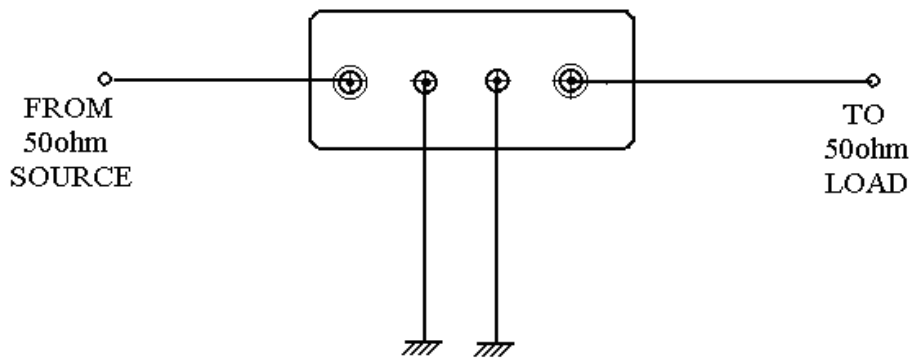
2-1. Electrical characteristics

	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	-	740	-
Insertion Loss (In Fc +/- 1.5 MHz)	dB		2.5	4.0
Amplitude Ripple (In Fc +/- 1.5 MHz)	dB		0.5	1.5
Relative Attenuation	dB			
0.3 MHz ~ 710 MHz		40	45	-
710 MHz ~747 MHz		18	25	
770 MHz ~ 1000 MHz		35	45	
Input/Output Impedance	Ohms		50	

2-2. Typical frequency response



3. TEST CIRCUIT



4. ENVIRONMENTAL CHARACTERISTICS

4-1 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +25°C for 5 Minutes and a higher temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 2-2.

4-2 Resistance to solder heat

Submerge the device terminals into the solder bath at 260°C ±5°C for 10±1 sec.

Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2-2.

4-3 Solderability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2-2.

4-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 2-2.

4-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 2-2.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.